

preliminary

Туре	Ag <sup>*</sup> Aİ <sup>*</sup>	V <sub>DRM</sub> / V <sub>RRM</sub>	V <sub>DSM</sub> / V <sub>RSM</sub> [V]	<b>/<sub>Т(AV)</sub></b> [А]	Chip Size [mm] x [mm]	Package Options	• <del> </del>
CWP 7-	12 🗸	1200	1300	19	4.45 4.45	sawn on foil  unsawn wafer  in waffle pack	
	*Frontside options					*Please contact IXYS chip sales	

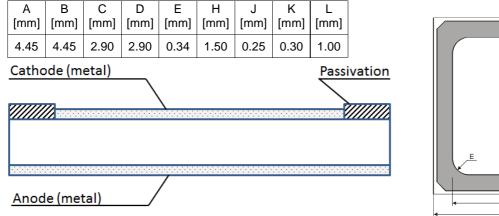
## **Mechanical Parameters**

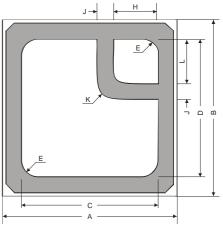
Area active		0	0.06	cm <sup>2</sup>	1////	
Area total		0	).20	cm <sup>2</sup>		
Wafer size Ø		1	150	mm	Features	
Thickness	290 μm Si			<ul> <li>planar passivate and channelstop</li> </ul>		
Material						
Max. possible chips per wafer	682			Planar front and		
Passivation front side	Glassivation				Non-structured     non-structured	
Metallization top side	solderable: Ti / Ni / Ag *			on full area botto		
top side	I	bondable: 4 µm	ΑI			
Recom. wire bonds (AI)	Cathode Gate					
Number / Ø [μm]	6 / 300	1 / 3	300		Applications	
Metallization backside	solderal	ble (only):Ti / Ni /	Ag *		DC motor contro	
Reject Ink Dot Size		Ø 0.4-	-1.0	mm	AC power contro	
Recom. Storage Environment					<ul><li>Softstart AC mot</li><li>Light, heat and t</li></ul>	
sawn on foil	in org. container, in	dry nitrogen	< 6	month	<b>3</b> /	
unsawn wafer	in org. container, in	dry nitrogen	< 2	year		
in waffle pack	in org. container, in	dry nitrogen	< 2	year		
·	T <sub>stg</sub>	-40	40	°C		
	ary .					

- ted with guardring
- d back surface
- anode contact tom side
- rol
- rol
- otor controller
- temperature control

## \*Sinterable top/bottom side on request

### **Dimensions**





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			Ratings				
Symbol	Conditions	min.	typ.	max.			
I <sub>R</sub>	$V_D = Vr = Vrr$	$T_{VJ} = 25^{\circ}C$ $T_{VJ} = 150^{\circ}C$		0.05 5			
V <sub>7</sub>	I <sub>T</sub> = 20 A	$T_{VJ} = 25 ^{\circ}\text{C}$ $T_{VJ} = 150 ^{\circ}\text{C}$	40	1.27 1.24			
V <sub>To</sub>		s calculations only		0.86			
r,	T <sub>v.j</sub> = 150 °C			19.00	m		
V <sub>G7</sub>	$V_D = 6 \text{ V}$	T <sub>v.i</sub> = 25°C	79	1.5			
	_	$T_{VJ} = -40$ °C		2.5			
l <sub>gī</sub>	$V_D = 6 V$	$T_{v_{J}} = 25^{\circ}C$ 13		24	m		
G/		$T_{VJ} = -40$ °C		50	m		
<b>V</b> <sub>GD</sub>	T <sub>vJ</sub> = 125 °C	$V = \frac{2}{3} V_{DRM}$		0.2			
l <sub>gD</sub>				4	n		
I <sub>L</sub>	t <sub>p</sub> =10 μs	$T_{VJ} = 25^{\circ}C$ $I_{G} = 0.1 \text{ A di}_{G}/dt = 0.1 \text{ A/}\mu\text{s}$		75	n		
I <sub>H</sub>	R <sub>GK</sub> = ∞	$T_{VJ} = 25^{\circ}C$ $V_{D} = 6 \text{ V}$		60	n		
t <sub>gd</sub>	$V_D = \frac{1}{2} V_{DRM}$			2			
		$di_{g}/dt = 0.5 A/\mu$					
t <sub>q</sub>	-	$I_{T} = 20 \text{ A}$ -di/dt = 10 A/µs		150			
-4	$t_p = 200  \mu s$	$dv/dt = V/\mu s V_D = \frac{2}{3} V drm T_{V,J} = 125 °C$					
(di/dt) <sub>a</sub>	repetitive	$I_T = 20$ A		100	A/ı		
	non repetitive	I <sub>T</sub> = 19 A		500	A/ı		
	$V = \frac{2}{3} V_{DRM}$	$T_{VJ} = 150 ^{\circ}\text{C}$ $di_{G}/dt = 0.1 \text{A/}\mu\text{s}$					
	$I_G = 0.1 A$	$t_p = 200 \ \mu s$ $f = 50 \ Hz$					
(dv/dt) <sub>cr</sub>	$T_{VJ} = 150  ^{\circ}C$	$V_{DR} = \frac{2}{3} V_{DRM}$		500	V/ا		
	R <sub>GK</sub> = ∞	method 1 (linear voltage rise)					
$P_{\sf GM}$	$T_{VJ} = 125 ^{\circ}\text{C}$	$t_p = 30 \mu s$		10	,		
		$t_p = 3E \mu s$		5	'		
P <sub>GAV</sub>				0.5	'		
V <sub>rgm</sub>				10			
T <sub>V</sub> J		-40		150	ď		
I <sub>T(AV)</sub>	$T_{\rm C} = 100 ^{\circ} \text{C}$	180° rect.		19			
	T <sub>vJ</sub> = 150 °C	180° sine		18			
I <sub>TSM</sub> *	$T_{VJ} = 45^{\circ}C$	t = 10 ms (50) Hz, sine		180			
	$V_R = 0 V$	t = 8.3 ms (60) Hz, sine		210			
	T <sub>VJ</sub> = 150 °C	t = 10 ms (50) Hz, sine		170			
	$V_R = 0 V$	t = 8.3 ms (60) Hz, sine		180			
Pt *	$T_{VJ} = 45^{\circ}C$	t = 10 ms (50) Hz, sine		162	Α		
	$V_R = 0 V$	t = 8.3 ms (60) Hz, sine		183	Α		
	T <sub>VJ</sub> = 150 °C	t = 10 ms (50) Hz, sine		145	Α		
	$V_R = 0 V$	t = 8.3 ms (60) Hz, sine		134	Α		

<sup>\*</sup> Data according to assembled product CS 19

Data according to IEC 60747



# **Thyristor Chip**

**CWP 7-12** 

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#### **Terms of Conditions and Usage**

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Should you intend to use the product in aviation applications, in health or life endangering or life support applications, please notify. For any such applications we urgently recommend

- to perform joint risk and quality assessments;
- the conclusion of quality agreements;
- to establish joint measures to ensure application specific product capabilities and notify that IXYS may delivery dependent on the realization of any such measures.